

## Electronic Acknowledgement Receipt

<b>EFS ID:</b>	9289642
<b>Application Number:</b>	10055560
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	6103
<b>Title of Invention:</b>	INTEGRATED CHIP PACKAGE STRUCTURE USING METAL SUBSTRATE AND METHOD OF MANUFACTURING THE SAME
<b>First Named Inventor/Applicant Name:</b>	Mou-Shiung Lin
<b>Customer Number:</b>	89518
<b>Filer:</b>	Dennis Alan Duchene/Patricia Balero
<b>Filer Authorized By:</b>	Dennis Alan Duchene
<b>Attorney Docket Number:</b>	085027-0058
<b>Receipt Date:</b>	24-JAN-2011
<b>Filing Date:</b>	22-JAN-2002
<b>Time Stamp:</b>	13:59:20
<b>Application Type:</b>	Utility under 35 USC 111(a)

### Payment information:

Submitted with Payment	no
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### File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1		DolceralInformationDisclosureStatement-085027-0058.pdf	166992 <small>8d98ba864570215a0f1c02b61453c251fb 8ee</small>	yes	5

	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Transmittal Letter		1	3	
	Information Disclosure Statement (IDS) Filed (SB/08)		4	5	
Warnings:					
Information:					
2	Foreign Reference	TW385509_FRN00123.pdf	6828863 d5c0f025a2145d46db1431131ff1e2723d94e8	no	53
Warnings:					
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3	Foreign Reference	TW417265_FRN00124.pdf	2756476 210a7d108961e71780a7805f8cac01116325a	no	26
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4	Foreign Reference	TW449894_FRN00122.pdf	2918238 912b22c98095e045d44751d45c046939c348263	no	28
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	Multipart Description/PDF files in .zip description				
	Document Description		Start	End	
	Transmittal Letter		1	2	
	Information Disclosure Statement (IDS) Filed (SB/08)		3	4	
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6		TS-5InformationDisclosureStatement-085027-0058.pdf	159434 6c6e411370e0977235e4666c3eede01341d5d974a	yes	4
	Multipart Description/PDF files in .zip description				
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	Transmittal Letter		1	2	

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7	OrphanInformationDisclosureStatement-085027-0058.pdf	188724 78b24b674c72008ba51c5c3e32a6d7d11b5c7	yes 5
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<b>Document Description</b>		<b>Start</b>	<b>End</b>
Transmittal Letter		1	2
Information Disclosure Statement (IDS) Filed (SB/08)		3	5
<b>Warnings:</b>			
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8	NPL Documents	1_MISTRY_45nm_logic.pdf 2254221 072127b124142b4f448b16305577e0d07281092	no 4
<b>Warnings:</b>			
<b>Information:</b>			
9	NPL Documents	2_EDELSTEIN_Advantages_of_Copper.pdf 3696109 d4a312104b1d94203a708a79e6919e164c5506874	no 9
<b>Warnings:</b>			
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10	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf 4517666 1a3408bd7c70e1547170da4bce4129a5c08aaae074	no 7
<b>Warnings:</b>			
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11	NPL Documents	4_GAO_An_improved_electrostatic_discharge_protection_structure.pdf 885848 7895c75db4f53d7c0b64f5e1851853ca9779e045	no 6
<b>Warnings:</b>			
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12	NPL Documents	5_YOEH_Copper_Die_Bumps.pdf 717153 6ea0b2af4c3f93cd3e1b0b46cc4bb4b118ee20ba	no 5
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13	NPL Documents	6_HU_Copper_Polyimide.pdf 436455 60f08badc448063bc25d62121b1776c267a05	no 7
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14	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 8112031f7462473ca0d1a0f10c24a5e457f6ab27	no	8
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16	NPL Documents	9_YEOH_ESD_effects_on_power_supply_clamps.pdf	226994 ab271bc6a48720a8f86f0f8476e6d45c395eeb65	no	4
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19	NPL Documents	12_JENEI_HighQInductors.pdf	279415 1749c7db8f20de3cc0b6d674bc37238efb411	no	3
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20	NPL Documents	13_GROVES_HighQ_Inductors_in_a_SiGE_BiCMOS_process.pdf	420788 8c26f26d60459c3cd7d159d587c4a335995f46e	no	4
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31	NPL Documents	24_PDF_MALONEY_Stacked_P_MOS_clamps_for_high_voltage_power_supply_protection_pdf.pdf	1327621 bf725db3043890a026a150438d3d230cbdb8	no	8
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33	NPL Documents	26_PDF_MEGICA_Brochure_lea flets_01_28_04_pdf.pdf	888383 ae019845e67d817d512ee9f652144d85c1815489a	no	3
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34	NPL Documents	27_PDF_LIN_Post_Passivation_ Technology_Presentation_for_ TSMC_Tech_Symposium_2003 _pdf.pdf	1277639 20556e2754a0807ec288cc5487d24d52717e89	no	32
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35	NPL Documents	28_PDF_LIN_A_New_IC_Interc onnection_Scheme_and_Desig n_pdf.pdf	116206 e1e1d4bb6cc0007c70b6677a10a8a67106ee0d8	no	4
<b>Warnings:</b>					
<b>Information:</b>					
<b>Total Files Size (in bytes):</b>			53953303		
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p><b><u>New Applications Under 35 U.S.C. 111</u></b>          If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p><b><u>National Stage of an International Application under 35 U.S.C. 371</u></b>          If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p><b><u>New International Application Filed with the USPTO as a Receiving Office</u></b>          If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					